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WHAT IS CLAIMED IS:

- 1. A resin-encapsulated semiconductor device,
 comprising:
 - a die pad;
- a semiconductor chip mounted on the die pad;
 - a first lead including a first bonding pad provided on an upper surface of the first lead and a first land provided on a lower surface of the first lead;
 - a second lead including a second bonding pad provided on an upper surface of the second lead and a second land provided on a lower surface of the second lead;
 - a third lead including a third bonding pad provided on an upper surface of the third lead and a third land provided on a lower surface of the third lead;

thin metal wires each connecting the bonding pad of each lead to a portion of the semiconductor chip; and

an encapsulation resin for encapsulating the semiconductor chip, the leads, the thin metal wires and the die pad,

- wherein the first lead and the third lead are separated from each other, with one end of the first lead being exposed on a surface of the encapsulation resin and both ends of the third lead being in the encapsulation resin.
- 2. The resin-encapsulated semiconductor device of claim 1, wherein at least the second lead includes a neck portion having a smaller width than other portions as viewed

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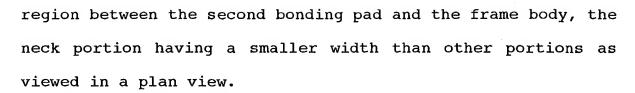
in a plan view.

- 3. The resin-encapsulated semiconductor device of claim 1, wherein each lead includes a region around the bonding pad thereof that has a smaller thickness than that of a portion of the lead corresponding to the bonding pad, with a stepped portion being provided between the bonding pad and the region around the bonding pad.
- 4. The resin-encapsulated semiconductor device of claim 1, wherein the first, second and third lands are exposed on a lower surface of the encapsulation resin while being arranged in three rows as viewed in a plan view.
- 5. The resin-encapsulated semiconductor device of claim 1, wherein the second lead and a lead structure including the first and third leads are arranged alternately along a periphery of an opening of a frame body.
- 6. A method for manufacturing a resin-encapsulated semiconductor device, comprising the steps of:
- (a) preparing a lead frame, wherein the lead frame includes a frame body with a plurality of openings therein, and a die pad and a group of leads provided in each of the openings, the group of leads including: a first lead including a first bonding pad provided on an upper surface of the first lead and a first land provided on a lower surface of the first lead; a second lead including a second bonding pad provided on an upper surface of the second lead and a second land provided on a lower surface of the second lead;

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and a third lead connected to the first lead and including a third bonding pad provided on an upper surface of the third lead and a third land provided on a lower surface of the third lead;

- (b) attaching an encapsulation sheet on a lower surface of the lead frame;
- (c) mounting a semiconductor chip on the die pad in each opening;
- (d) electrically connecting each of a plurality of portions of each semiconductor chip to one of the first to third bonding pads via a thin metal wire;
- (e) encapsulating the semiconductor chips, the leads, the thin metal wires and the die pads in the respective openings with an encapsulation resin, thereby producing an encapsulated structure;
 - (f) removing the encapsulation sheet;
- (g) dividing the entire encapsulated structure obtained in the step (e) into individual resin-encapsulated semiconductor devices; and
- 20 (h) after the step (b) and before the step (e), cutting off a connecting portion between the first lead and the third lead, thereby electrically separating the first lead and the third lead from each other.
- 7. The method for manufacturing a resin-encapsulated semiconductor device of claim 6, wherein in the step (a), a neck portion is provided at least in the second lead in a



- 8. The method for manufacturing a resin-encapsulated semiconductor device of claim 6, wherein in the step (a), a stepped portion is provided between a region of each lead around the bonding pad of the lead and a portion of the lead corresponding to the bonding pad.
- 9. The method for manufacturing a resin-encapsulated semiconductor device of claim 6, wherein in the step (a), the second lead and a lead structure including the first and third leads are arranged alternately along a periphery of each opening of the frame body.
- 10. The method for manufacturing a resin-encapsulated semiconductor device of claim 6, wherein in the step (g), the encapsulated structure is cut by a rotating blade.